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## SN74ALVC164245-EP 16-BIT 2.5-V TO 3.3-V/3.3-V TO 5-V LEVEL-SHIFTING TRANSCEIVER WITH 3-STATE OUTPUTS

SCAS774A-JUNE 2004-REVISED SEPTEMBER 2005

#### **FEATURES DGG OR DL PACKAGE Controlled Baseline** (TOP VIEW) - One Assembly/Test Site, One Fabrication 48 10E 1DIR [ 1B1 **∏** 2 47∏ 1A1 **Enhanced Diminishing Manufacturing** 1B2**∏**3 46 ¶ 1A2 Sources (DMS) Support GND ∏ 4 45 GND **Enhanced Product-Change Notification** 1B3 **∏** 5 44 1 1A3 Qualification Pedigree(1) 43 1A4 1B4 [ Member of the Texas Instruments Widebus™ (3.3 V, 5 V) V<sub>CCB</sub> 42 V<sub>CCA</sub> (2.5 V, 3.3 V) **Family** 1В5 Г 8 41**∏** 1A5 Max t<sub>pd</sub> of 5.8 ns at 3.3 V 1B6 [ 40**∏** 1A6 GND [] 10 39 GND ±24-mA Output Drive at 3.3 V 1B7 [ 11 38**∏** 1A7 Control Inputs VIH/VIL Levels Are Referenced 1B8 **∏** 12 37 T 1A8 to V<sub>CCA</sub> Voltage 2B1 **1** 13 36 2A1 Latch-Up Performance Exceeds 250 mA Per 2B2 [ 35 2A2 14 JESD 17 GND **1**5 34 GND (1) Component qualification in accordance with JEDEC and 2B3 **1** 16 33 7 2A3 industry standards to ensure reliable operation over an 32 1 2A4 2B4 **∏** 17 extended temperature range. This includes, but is not limited 31 V<sub>CCA</sub> (2.5 V, 3.3 V) to, Highly Accelerated Stress Test (HAST) or biased 85/85, (3.3 V, 5 V) V<sub>CCB</sub> 18 temperature cycle, autoclave or unbiased HAST, 2B5 **1** 19 30 2A5 electromigration, bond intermetallic life, and mold compound 2B6 **1**20 29 2A6 life. Such qualification testing should not be viewed as justifying use of this component beyond specified GND Π 21 28**∏** GND performance and environmental limits. 2B7 **∏** 22 27 1 2A7 2B8 **∏** 23 26 2A8 2DIR [ 25 20E

### **DESCRIPTION/ORDERING INFORMATION**

This 16-bit (dual-octal) noninverting bus transceiver contains two separate supply rails. B port has  $V_{CCB}$ , which is set to operate at 3.3 V and 5 V. A port has  $V_{CCA}$ , which is set to operate at 2.5 V and 3.3 V. This allows for translation from a 2.5-V to a 3.3-V environment, and vice versa, or from a 3.3-V to a 5-V environment, and vice versa.

The SN74ALVC164245 is designed for asynchronous communication between data buses. The control circuitry (1DIR, 2DIR,  $\overline{10E}$ , and  $\overline{20E}$ ) is powered by  $V_{CCA}$ .

To ensure the high-impedance state during power up or power down, the output-enable  $(\overline{OE})$  input should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAG	E <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
4000 1- 0500	SSOP - DL	Reel of 1000	CALVC164245IDLREP	ALVC164245	
	TSSOP - DGG	Reel of 2000 CALVC164245IDGGREP		ALVC164245	
–40°C to 85°C	VFBGA – GQL	Dool of 1000	CALVC164245IGQLREP	VC4245ED	
	VFBGA – ZQL (Pb-free)	Reel of 1000	CALVC164245IZQLREP	VC4245EP	
-55°C to 125°C	TSSOP – DGG	Reel of 2000	CALVC164245MDGGREP	C164245MEP	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.





## GQL OR ZQL PACKAGE (TOP VIEW)

	_	1	2	3	4	5	6
Α		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\circ$
В		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
С		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
D		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
Е		$\bigcirc$	$\bigcirc$			$\bigcirc$	$\bigcirc$
F		$\bigcirc$	$\bigcirc$			$\bigcirc$	$\bigcirc$
G		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
Н		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
J		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
K		$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$	$\bigcirc$
	<b>\</b> _						

### TERMINAL ASSIGNMENTS(1)

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 <del>OE</del>
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V <sub>CCB</sub>	V <sub>CCA</sub>	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
н	2B5	2B6	V <sub>CCB</sub>	$V_{CCA}$	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 <del>OE</del>

(1) NC - No internal connection

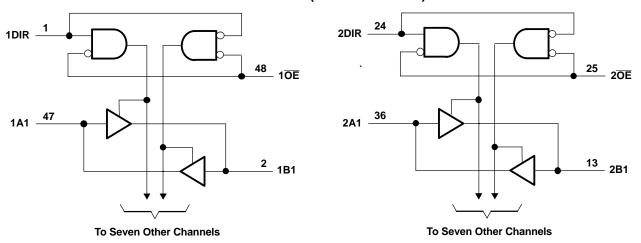
## FUNCTION TABLE (EACH 8-BIT SECTION)

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation





### **LOGIC DIAGRAM (POSITIVE LOGIC)**



Pin numbers shown are for the DGG and DL packages.

## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range for  $V_{CCB}$  at 5 V and  $V_{CCA}$  at 3.3 V (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA}$	Cumply valtage range		-0.5	4.6	V
$V_{CCB}$	Supply voltage range		-0.5	6	V
		Except I/O ports (2)	-0.5	6	
$V_{I}$	Input voltage range	I/O port A <sup>(3)</sup>	-0.5	V <sub>CCA</sub> + 0.5	V
		I/O port B <sup>(2)</sup>	-0.5	V <sub>CCB</sub> + 0.5	
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		<b>–</b> 50	mA
I <sub>OK</sub>	Output clamp current	current V <sub>O</sub> < 0		<b>–</b> 50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or GND			±100	mA
		DGG package		70	
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DL package		63	°C/W
		GQL/ZQL package		42	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

This value is limited to 6 V maximum.

This value is limited to 4.6 V maximum.

The package thermal impedance is calculated in accordance with JESD 51-7.



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## Recommended Operating Conditions<sup>(1)</sup>

for  $\rm V_{\rm CCB}$  at 3.3 V and 5 V

			MIN	MAX	UNIT
$V_{CCB}$	Supply voltage		3	5.5	٧
V <sub>IH</sub> High-level input voltage			2		V
V	Low-level input voltage	<sub>CB</sub> = 3 V to 3.6 V		0.7	V
V <sub>IL</sub>	V <sub>CCI</sub>	<sub>CB</sub> = 4.5 V to 5.5 V		0.8	v
$V_{IB}$	Input voltage				V
$V_{OB}$	V <sub>OB</sub> Output voltage				V
I <sub>OH</sub>	High-level output current			-24	mA
I <sub>OL</sub>	Low-level output current			24	mA
Δt/Δv Input transition rise or fall rate				10	ns/V
T <sub>A</sub>	Operating free air temperature	_VC16245I	-40	85	°C
'A	Operating free-air temperature CALVC16245M			125	C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

## Recommended Operating Conditions<sup>(1)</sup>

for  $V_{\text{CCA}}$  at 2.5 V and 3.3 V

			MIN	MAX	UNIT
$V_{CCA}$	Supply voltage		2.3	3.6	V
M	High level input valtage	V <sub>CCA</sub> = 2.3 V to 2.7 V	1.7		V
V <sub>IH</sub>	High-level input voltage	V <sub>CCA</sub> = 3 V to 3.6 V	2		V
V	Low level input veltage	V <sub>CCA</sub> = 2.3 V to 2.7 V		0.7	V
V <sub>IL</sub>	Low-level input voltage	V <sub>CCA</sub> = 3 V to 3.6 V		0.8	V
$V_{IA}$	Input voltage				V
V <sub>OA</sub>	Output voltage		0	$V_{CCA}$	V
	High level output ourrent	V <sub>CCA</sub> = 2.3 V	0	-18	A
I <sub>OH</sub>	High-level output current	V <sub>CCA</sub> = 3 V		-24	mA
	Lavidaval autorit averant	V <sub>CCA</sub> = 2.3 V		18	Λ
I <sub>OL</sub>	Low-level output current	V <sub>CCA</sub> = 3 V		24	mA
Δt/Δν	Input transition rise or fall rate			10	ns/V
т	Operating free air temperature	CALVC16245I	-40	85	۰,۲
T <sub>A</sub>	Operating free-air temperature	CALVC16245M		125	°C

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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### **Electrical Characteristics**

over recommended operating free-air temperature range for  $V_{CCA}$  = 2.7 V to 3.6 V and  $V_{CCB}$  = 4.5 V to 5.5 V (unless otherwise noted)

D4.D		TEST SOMBITIONS		.,	CALV	C164245I	CALVO	164245M	I	
PARA	AMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	TYP <sup>(1)</sup> MAX	MIN	TYP <sup>(1)</sup>	MAX	UNIT
		I <sub>OH</sub> = -100 μA	2.7 V to 3.6 V		V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.2			
	B to A	I <sub>OH</sub> = -12 mA	2.7 V		2.2		2.2			
		10H = -12 111A	3 V		2.4		2.4			
$V_{OH}$		$I_{OH} = -24 \text{ mA}$	3 V		2		2			V
		I <sub>OL</sub> = 100 μA		4.5 V	4.3		4.3			
	A to B	ΙΟΣ = 100 μΑ		5.5 V	5.3		5.3			
	7 10 5	I <sub>OL</sub> = 24 mA		4.5 V	3.7		3.7			
		10L - 24 111A		5.5 V	4.7		4.7			
	D. ( - A	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V			0.2			0.2	
	B to A	I <sub>OL</sub> = 12 mA	2.7 V			0.4			0.4	
$V_{OL}$		I <sub>OL</sub> = 24 mA	3 V			0.55			0.55	V
VOL	A to B	I <sub>OL</sub> = 100 μA		4.5 V to 5.5 V		0.2			0.2	
		I <sub>OL</sub> = 24 mA		4.5 V to 5.5 V		0.55			0.55	
I <sub>I</sub>	Control inputs	$V_I = V_{CCA}/V_{CCB}$ or GND	3.6 V	5.5 V		±5			±5	μА
I <sub>OZ</sub> <sup>(2)</sup>	A or B port	$V_O = V_{CCA}/V_{CCB}$ or GND	3.6 V	5.5 V		±10			±10	μА
I <sub>CC</sub>		$V_I = V_{CCA}/V_{CCB}$ or GND, $I_O = 0$	5.5 V	5.5 V		40			40	μА
Δl <sub>CC</sub> <sup>(3</sup>	)	One input at $V_{CCA}/V_{CCB} - 0.6 \text{ V}$ , Other inputs at $V_{CCA}/V_{CCB}$ or GND	3 V to 3.6 V	4.5 V to 5.5 V		750			750	μА
C <sub>i</sub>	Control inputs	$V_I = V_{CCA}/V_{CCB}$ or GND	3.3 V	5 V		6.5		6.5		pF
C <sub>io</sub>	A or B port	$V_O = V_{CCA}/V_{CCB}$ or GND	3.3 V	3.3 V		8.5		8.5		pF

All typical values are at  $V_{CCA} = 3.3 \text{ V}$  and  $V_{CCB} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current. This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than at 0 or the associated  $V_{CC}$ .



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### **Electrical Characteristics**

over recommended operating free-air temperature range for  $V_{CCA}$  = 2.3 V to 2.7 V and  $V_{CCB}$  = 3 V to 3.6 V (unless otherwise noted)

DAD	AMETER	TEST CONDITIONS	V	V	CALVC164245I	CALVC164245M		UNIT
PARA	AMETER	TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	MIN MAX	MIN I	XAN	UNII
		$I_{OH} = -100 \mu A$	2.3 V to 2.7 V	3 V to 3.6 V	V <sub>CCA</sub> - 0.2	V <sub>CCA</sub> - 0.2		
	B to A	$I_{OH} = -8 \text{ mA}$	2.3 V	3 V to 3.6 V	1.7	1.7		
$V_{OH}$		I <sub>OH</sub> = -12 mA	2.7 V	3 V to 3.6 V	1.8	1.8		V
	A to B	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V	V <sub>CCB</sub> - 0.2	V <sub>CCB</sub> - 0.2		
	AIOB	I <sub>OL</sub> = 18 mA	2.3 V to 2.7 V	3 V	2.2	2.2		
	B to A	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V	0.2		0.2	
V		I <sub>OL</sub> = 12 mA	2.3 V	3 V to 3.6 V	0.6		0.6	V
V <sub>OL</sub>	A to B	I <sub>OL</sub> = 100 μA	2.3 V to 2.7 V	3 V to 3.6 V	0.2		0.2	V
		I <sub>OL</sub> = 18 mA	2.3 V	3 V	0.55		0.55	
I <sub>I</sub>	Control inputs	$V_{I} = V_{CCA}/V_{CCB}$ or GND	2.3 V to 2.7 V	3 V to 3.6 V	±5		±5	μΑ
I <sub>OZ</sub> <sup>(1)</sup>	A or B port	$V_{O} = V_{CCA}/V_{CCB}$ or GND	2.3 V to 2.7 V	3 V to 3.6 V	±10		±10	μΑ
I <sub>CC</sub>		$V_I = V_{CCA}/V_{CCB}$ or GND, $I_O = 0$	2.3 V to 2.7 V	3 V to 3.6 V	20		40	μА
Δl <sub>CC</sub> <sup>(2</sup>	2)	One input at V <sub>CCA</sub> /V <sub>CCB</sub> – 0.6 V, Other inputs at V <sub>CCA</sub> /V <sub>CCB</sub> or GND	2.3 V to 2.7 V	3 V to 3.6 V	750		750	μΑ

For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current. This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than at 0 or the associated  $V_{\text{CC}}. \\$ 



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## **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 4)

					CALVC	16245I			
DADAMETED	FROM	то	$V_{CCB} = 3.3 \text{ V} \\ \pm 0.3 \text{ V} \\ V_{CCA} = 2.5 \text{ V} \\ \pm 0.2 \text{ V} \\$		$V_{CCB}$ = 5 V $\pm$ 0.5 V				
PARAMETER	(INPUT)	(OUTPUT)			V <sub>CCA</sub> = 2.7 V		$V_{CCA}$ = 3.3 V $\pm$ 0.3 V		UNIT
			MIN MA	λX	MIN	MAX	MIN	MAX	
4	А	В	7	'.6		5.9	1	5.8	20
t <sub>pd</sub>	В	A	7	'.6		6.7	1.2	5.8	ns
t <sub>en</sub>	ŌĒ	В	11	.5		9.3	1	8.9	ns
t <sub>dis</sub>	ŌĒ	В	10	).5		9.2	2.1	9.5	ns
t <sub>en</sub>	ŌĒ	A	12	2.3		10.2	2	9.1	ns
t <sub>dis</sub>	ŌĒ	A	é	0.3		9	2.9	8.6	ns

### **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 4)

				CALVC16245M			
DADAMETER	FROM	то	V <sub>CCB</sub> = 3.3 V ± 0.3 V	V <sub>CCB</sub> = 5			
PARAMETER	(INPUT)	(OUTPUT)	V <sub>CCA</sub> = 2.5 V ± 0.2 V	V <sub>CCA</sub> = 2.7 V	$V_{CCA} = 3.3 V$ $\pm 0.3 V$		UNIT
			MIN MAX	MIN MAX	MIN	MAX	
4	Α	В	8.6	6.9	1	6.8	no
t <sub>pd</sub>	В	Α	8.6	7.7	1.2	6.8	ns
t <sub>en</sub>	ŌĒ	В	12.5	10.3	1	9.9	ns
t <sub>dis</sub>	ŌĒ	В	11.5	10.2	2.1	10.5	ns
t <sub>en</sub>	ŌĒ	Α	14.5	11.2	2	10.1	ns
t <sub>dis</sub>	ŌĒ	Α	11.3	11	2.9	10.6	ns

## **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	$V_{CCB} = 3.3 \text{ V}$ $V_{CCA} = 2.5 \text{ V}$ TYP	$V_{CCB} = 5 V$ $V_{CCA} = 3.3 V$ TYP	UNIT
		Outputs enabled (B)	$C_1 = 50 \text{ pF},  f = 10 \text{ MHz}$	55	56	
_	Power dissipation capacitance	Outputs disabled (B)	C <sub>L</sub> = 50 pr, T = 10 MHZ	27	6	
C <sub>pd</sub>	rower dissipation capacitance	Outputs enabled (A)	C 50 °F \$ 10 MHz	118	56	pF
		Outputs disabled (A)	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	58	6	

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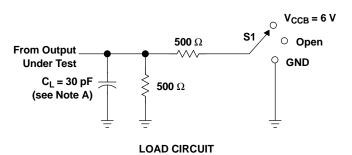
### Power-Up Considerations(1)

TI level-translation devices offer an opportunity for successful mixed-voltage signal design. A proper power-up sequence always should be followed to avoid excessive supply current, bus contention, oscillations, or other anomalies caused by improperly biased device pins. To guard against such power-up problems, take these precautions:

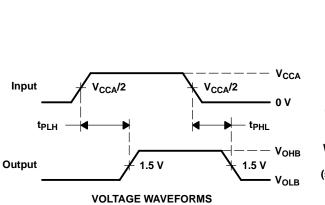
- 1. Connect ground before any supply voltage is applied.
- 2. Power up the control side of the device (V<sub>CCA</sub> for all four of these devices).
- 3. Tie  $\overline{OE}$  to  $V_{CCA}$  with a pullup resistor so that it ramps with  $V_{CCA}$ .
- 4. Depending on the direction of the data path, DIR can be high or low. If DIR high is needed (A data to B bus), ramp it with  $V_{CCA}$ . Otherwise, keep DIR low.
- (1) Refer to the TI application report, Texas Instruments Voltage-Level-Translation Devices, literature number SCEA021.

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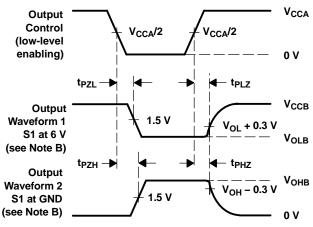
## PARAMETER MEASUREMENT INFORMATION $V_{CCA}$ = 2.5 V $\pm$ 0.2 V to $V_{CCB}$ = 3.3 V $\pm$ 0.3 V



TEST	S1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>CCB</sub> = 6 V
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND



**PROPAGATION DELAY TIMES** 



**VOLTAGE WAVEFORMS** 

**ENABLE AND DISABLE TIMES** 

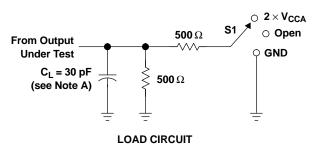
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz,  $Z_0 = 50 \Omega$ ,  $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

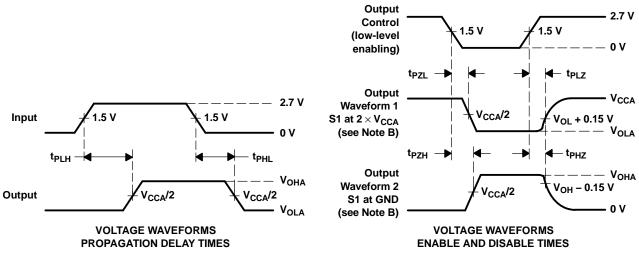
Figure 1. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CCB} = 3.3 \ V \pm 0.3 \ V$ to $V_{CCA} = 2.5 \ V \pm 0.2 \ V$



TEST	S1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	2×V <sub>CCA</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

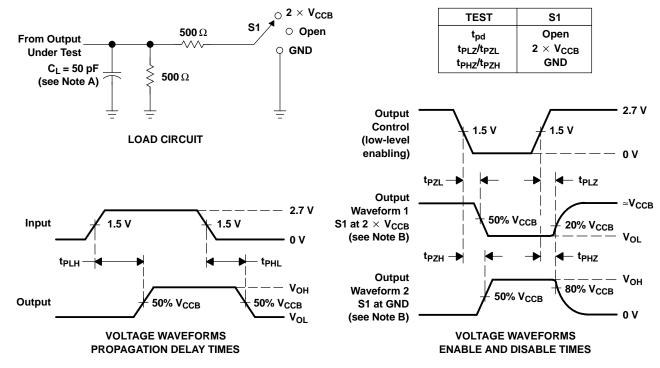


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR $\le$ 10 MHz,  $Z_0 = 50 \,\Omega$ ,  $t_r \le 2 \,$ ns,  $t_f \le 2 \,$ ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 2. Load Circuit and Voltage Waveforms

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## PARAMETER MEASUREMENT INFORMATION $V_{CCA}$ = 3.3 V $\pm$ 0.3 V to $V_{CCB}$ = 5 V $\pm$ 0.5 V



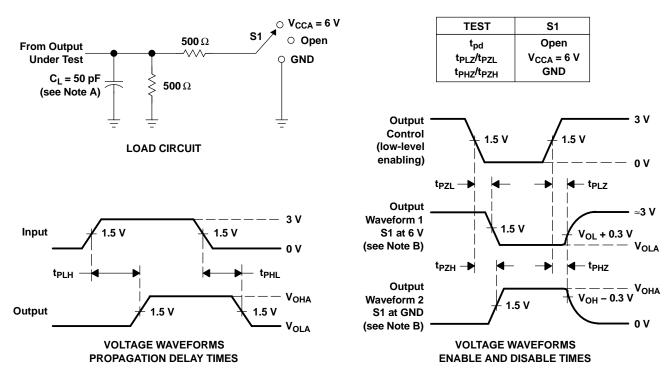
NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 3. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CCB}$ = 5 V $\pm$ 0.5 V to $V_{CCA}$ = 2.7 V and 3.3 V $\pm$ 0.3 V

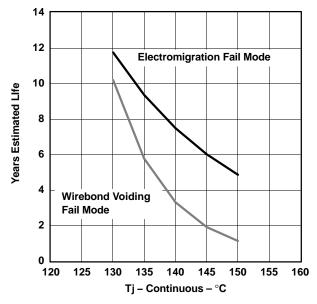


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O}$  = 50  $\Omega$ ,  $t_{f} \leq$  2.5 ns.  $t_{f} \leq$  2.5 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 4. Load Circuit and Voltage Waveforms

SCAS774A-JUNE 2004-REVISED SEPTEMBER 2005

# 74ALVC164245MDGG\*EP Estimated Device Life at Elevated Temperatures Electromigration and Wirebond Voiding Fail Modes



A. Silicon operating life design goal is 10 years at 105°C junction temperature.





10-Dec-2020

#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	U		Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
CALVC164245IDGGREP	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC164245	Samples
CALVC164245IDLREP	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC164245	Samples
CALVC164245MDGGREP	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	C164245MEP	Samples
V62/05612-01XE	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC164245	Samples
V62/05612-01YE	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVC164245	Samples
V62/05612-02YE	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	C164245MEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



## **PACKAGE OPTION ADDENDUM**

10-Dec-2020

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#### OTHER QUALIFIED VERSIONS OF SN74ALVC164245-EP:

Catalog: SN74ALVC164245

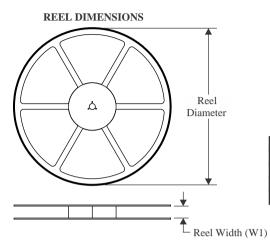
NOTE: Qualified Version Definitions:

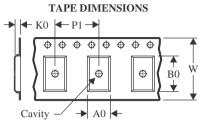
Catalog - TI's standard catalog product

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 4-Oct-2022

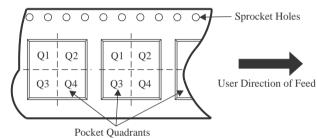
### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

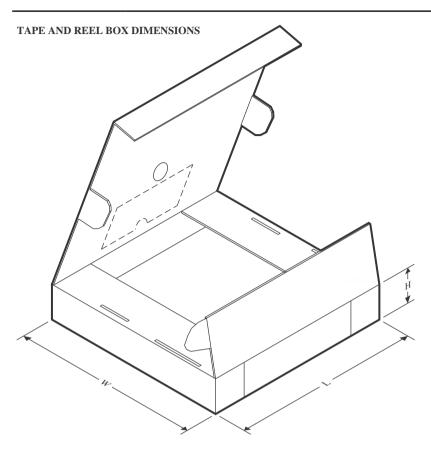
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CALVC164245IDGGREP	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
CALVC164245IDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
CALVC164245MDGGREP	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

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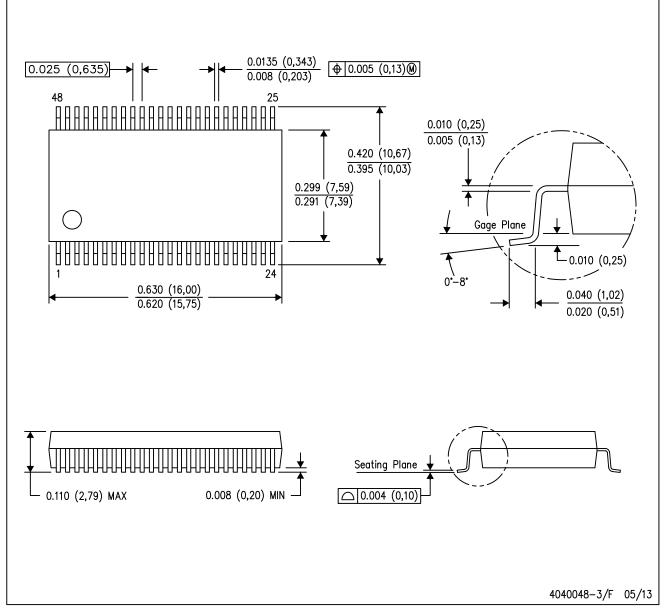


### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CALVC164245IDGGREP	TSSOP	DGG	48	2000	367.0	367.0	45.0
CALVC164245IDLREP	SSOP	DL	48	1000	367.0	367.0	55.0
CALVC164245MDGGREP	TSSOP	DGG	48	2000	356.0	356.0	41.0

## DL (R-PDSO-G48)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

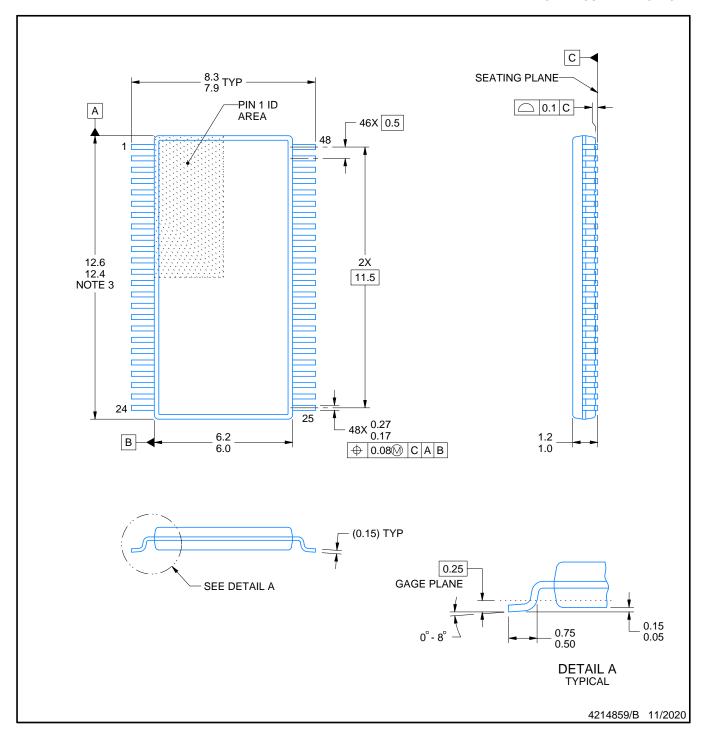
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



### NOTES:

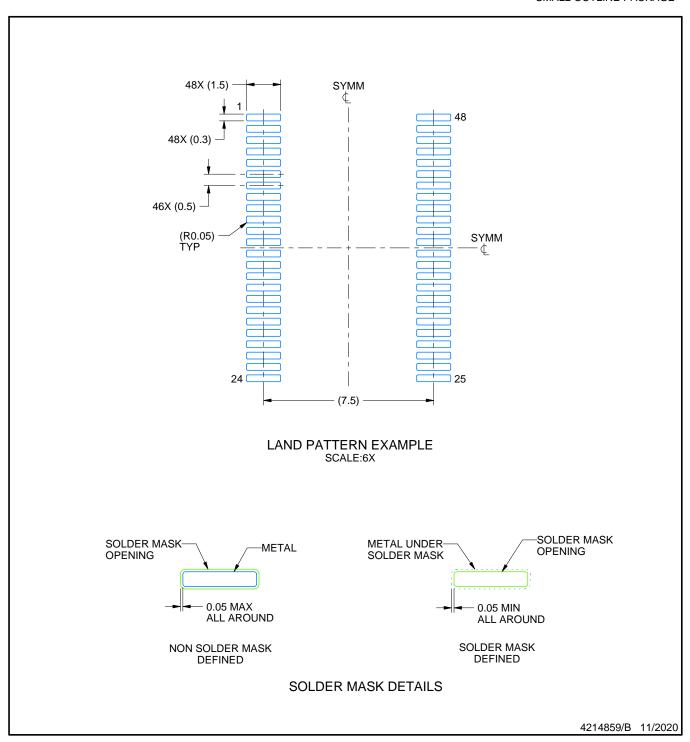
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE

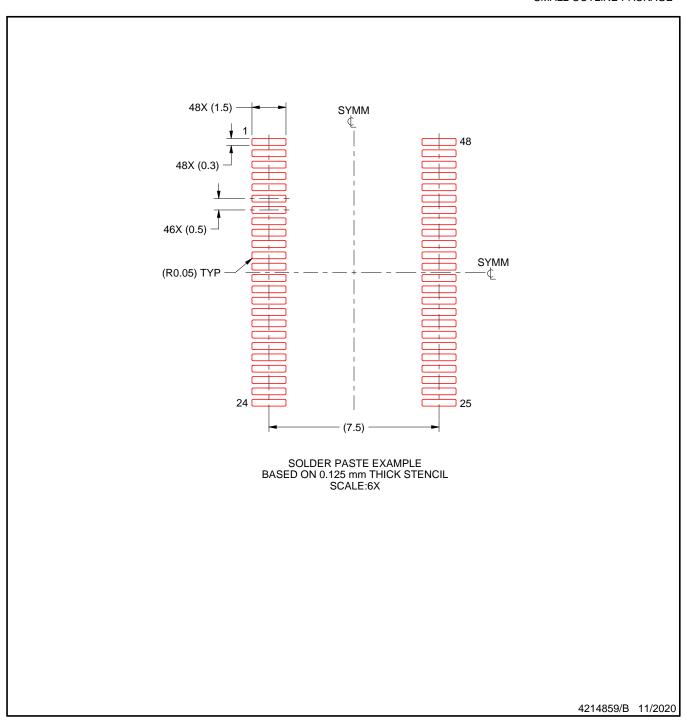


NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



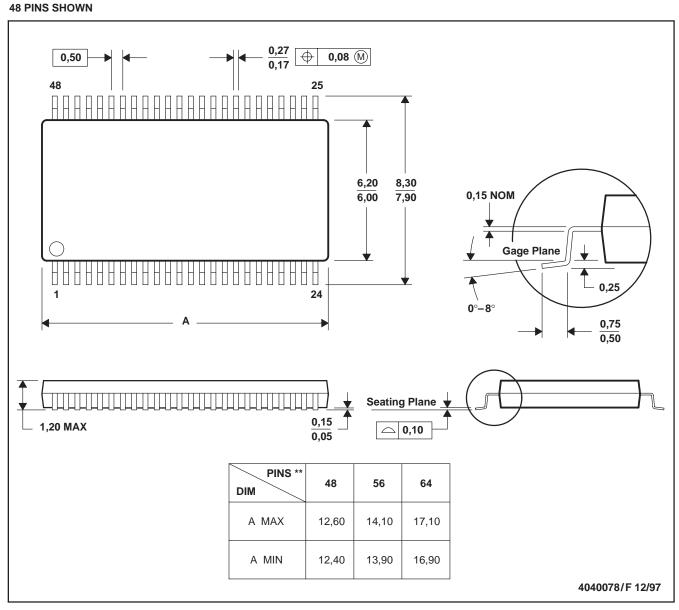
NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



### DGG (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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